DSC9G02

Silicon NPN epitaxial planar type

For high-frequency amplification DSC5G02 in SSMini3 type package

■ Features

- High transition frequency f_T
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

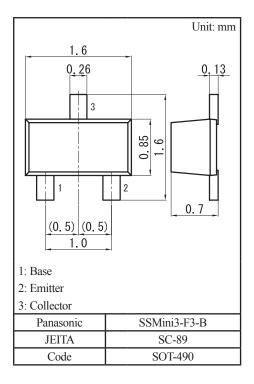
■ Marking Symbol: C5

Packaging

DSC9G02×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	V		
Collector-emitter voltage (Base open)	V _{CEO}	20	V	
Emitter-base voltage (Collector open)	$V_{\rm EBO}$	3	V	
Collector current	I_{C}	15	mA	
Collector power dissipation	P _C	125	mW	
Junction temperature	T_j	150	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



■ Electrical Characteristics $T_a = 25$ °C±3°C

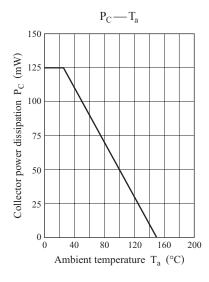
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu A, I_E = 0$	30			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$	3			V
Base-emitter voltage	$V_{ m BE}$	$V_{CE} = 6 \text{ V}, I_C = 1 \text{ mA}$		0.72		V
Forward current transfer ratio *1	h_{FE}	$V_{CE} = 6 \text{ V}, I_C = 1 \text{ mA}$	65		260	_
Transition frequency	f_T	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$	450	650		MHz
Reverse transfer capacitance (Common emitter)	C _{re}	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 10.7 \text{ MHz}$		0.6		pF
Power gain	PG	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		24		dB
Noise figure	NF	$V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$		3.3		dB

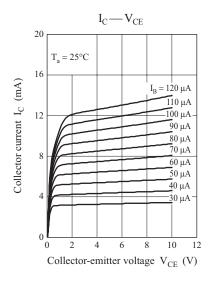
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

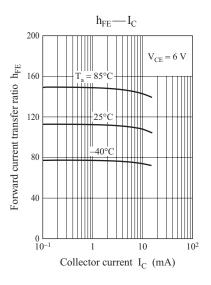
2. *1: Rank classification

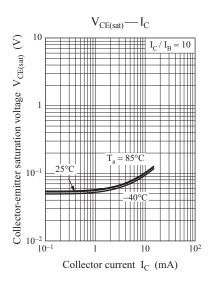
Code	С	D	0	
Rank	С	D	No-rank	
h_{FE}	65 to 160	100 to 260	65 to 260	
Marking Symbol	C5C	C5D	C5	

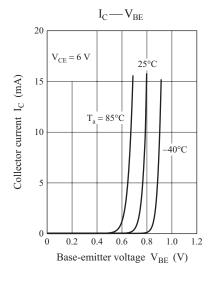
Product of no-rank is not classified and have no marking symbol for rank.

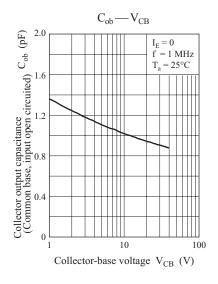


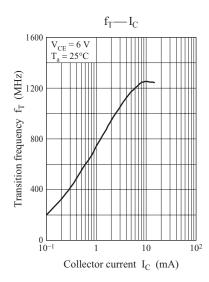








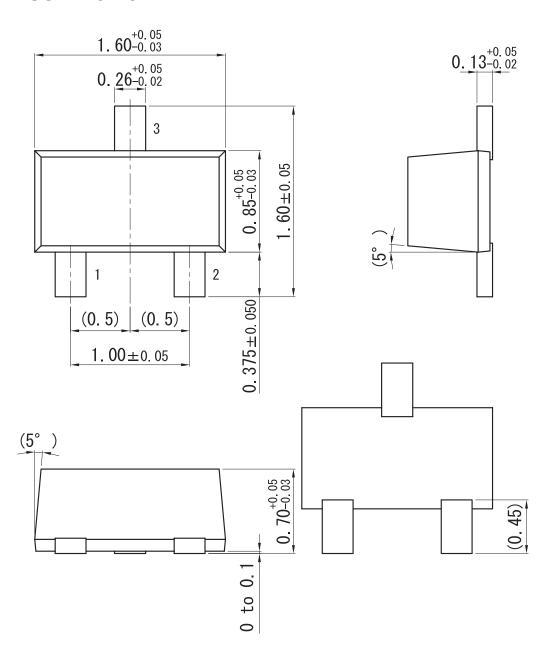




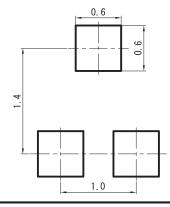
Ver. BED 2

SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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